TECHNICAL DATA SHEET **My-T-Bond® 2722** Low Exothermic Potting Compound October 2020



My-T-Bond[®] 2722 is a solvent free, low viscosity two component epoxy adhesive with moderate work life and slow cure at ambient temperature. My-T-Bond 2722 A/B is a specially formulated and processed to obtain void free casting, potting encapsulated components. It is ready to use system having low viscosity at processing temperature and becomes a viscous liquid which, after curing, takes the form of a hard and durable material. My-T-Bond 2722 has excellent resistance to oil, water & wide variety of solvents. The cured polymer shows good mechanical, electrical & chemical properties.

Special Features:

- Low Exothermic
- Low Viscosity
- Excellent resistant to water, oil and different solvents

Applications:

My-T-Bond 2722 A+B is suitable for Potting, Encapsulation & coating

- Potting of auto electrical components
- Casting of switch gear components and insulators
- Potting of instrument transformers
- Cable joint insulation, with all types of cables such as PILC, PVC, and Rubber insulated
- Topping of capacitors as sealant.

Properties

Technology	:	Epoxy
Cure	:	Ambient Temperature
Consistency	:	Viscous Liquid
Component	:	Two Part- Resin and
		Hardener
Color	:	Black
Mixing Ratio by	:	2:1 /4:1/ 3:1
weight		
Total cure at 25±2 °C	:	24 hours
Service Temperature	:	-30 to 150°C



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Physical Properties

Properties	Part A	Part B
Sp Gravity @ 25 °C	1.06	1.06
Viscosity, Brookfield	11300-14500	2750-4000
DVII+ Pro @ 25±2°C,	cP	cP
S/6, r.p.m. 20		

Mixing Ratio and Processing

Mixing we	Ratio by eight	Pot life	Total cure	Hardness ASTM
Part A Resin	Part B Hardener	(min)		D-2240, Shore D
At room	temperatur	e (25°C)		
100	50	65	8 hrs	70-80
		min		
80	20	90	20 hrs	70-80
		min		
75	25	75	24 hrs	70-80
		min		
At 60°C	Temperatu	ıre		
100	50	12	18	65-75
		min	min	
80	20	16	20	70-80
		min	min	
75	25	15	20	65-75
		min	min	
At 80 ^o C Temperature				
100	50	12	15	65-80
		min	min	
80	20	14	18	65-80
		min	min	
75	25	15	20	65-80
		min	min	

For all mixing ratio, the hardener is required to be mixed in Resin compound at room temperature and the mixture used within the specified pot life.

Recommended Curing Schedule

Or at $25\pm2^{\circ}$	C: 6-10 hours
Or at 60° C	: 2-3 hours
Or at 80° C	: 20 - 45 min

The curing schedules suggested are for general Guidance. In case of casting, it is recommended to give a post cure of about 30 min at 80°C after curing for 10 hours at room temperature.

The hardening of resin + Hardener mixture takes place much earlier than the suggested curing time. Hence the demolding operation or handling of the cast or potted component can be done earlier. This time should be decided in each case depending upon the mass, ambient temperature and the resin + Hardener system.

Directions for Use

- For best performance surfaces for bonding should be clean, dry and free of grease
- Part A and Part B must be blended/stirred separately first before mixing every time material is drawn for use.
- Using bulk containers, mix thoroughly by weight or volume in the proportions specified in properties of uncured material section. For hand mixing, weigh or measure out the desired amount of Part A and Part B mix thoroughly. Mix approximately 5 to 7 min after uniform color is obtained.
- Mix small quantity at a time, so that the mixed material is consumed within a work life / pot life time.
- Do not mix quantities greater than 4 kg as excessive heat build-up can occur and shorten the work life. Mixing smaller quantities will minimize the heat build-up.
- Pour the adhesive as quickly as possible after mixing. Parts should be assembled immediately after mixed adhesive has been applied.
- Keep the potted components from moving during cure. The joint should be allowed to develop full strength before subjecting to any service loads.
- Excess uncured adhesive can be wiped away with organic solvent (e.g. acetone / MEK).
- After use and before adhesive hardens mixing and dispensing equipment should be cleaned with hot soapy water.

Pack Size

My-T-Bond[®] 2722 is available in 250 g, 1kg, 2 kg, 5 kg, 10 kg & 50 Kg containers in polyethylene containers / HDPE Drum.

Storage and Handling

- Store product in a cool and dry location in unopened containers (particularly Part B) at room temperature.
- Keep away from moisture, direct sunlight & heat.
- My-T-Bond[®] 2722 will exhibit a shelf life of twelve months from the date of manufacture when stored in unopened original container at 25±2 °C.
- To prevent contamination of unused product, do not return any material to its original container.

For further specific information, contact our technical service centre.

Direct contact with skin should be avoided by using rubber gloves and goggles. Affected areas of skin should be scrubbed with 5% acetic acid and washed with plenty of water and soap. For detailed see MSDS.

Note

All statements, technical information and recommendations set forth herein are based on tests which Metlok Private Limited, believes to be reliable. However, Metlok Private Limited does not guarantee their accuracy or completeness. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In no case will Metlok Private Limited be liable for direct, consequential economic or other damages. *****

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